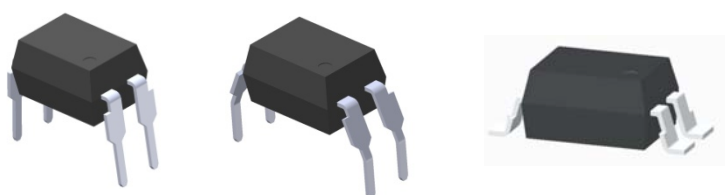
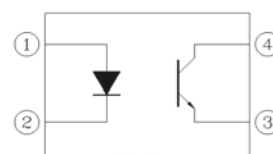


4 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLER EL817 Series



Schematic



Pin Configuration

1. Anode
2. Cathode
3. Emitter
4. Collector

Features:

- Compliance Halogens Free (Only copper leadframe)
(Br < 900 ppm, Cl < 900 ppm, Br+Cl < 1500 ppm)
- Current transfer ratio
(CTR: 50~600% at $I_F = 5\text{mA}$, $V_{CE} = 5\text{V}$)
- High isolation voltage between input and output (Viso = 5000Vrms)
- Creepage distance > 7.62mm
- Operating temperature up to +110°C
- Compact small outline package
- Pb free
- The product itself will remain within RoHS compliant version
- Compliance with EU REACH
- UL and cUL approved(No.E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CQC approved

Description

The EL817 Series of devices each consist of an infrared emitting diodes, optically coupled to a phototransistor detector. They are packaged in a 4-pin DIP package and available in wide-lead spacing and SMD option.

Applications

- Programmable controllers
- System appliances, measuring instruments
- Telecommunication equipments
- Home appliances, such as fan heaters, etc.
- Signal transmission between circuits of different potentials and impedances

Absolute Maximum Ratings (Ta=25°C)

	Parameter	Symbol	Rating	Unit
Input	Forward current	I _F	60	mA
	Peak forward current (1us, pulse)	I _{FP}	1	A
	Reverse voltage	V _R	6	V
	Power dissipation	P _D	100	mW
	Derating factor (above T _a = 100°C)		2.9	mW/°C
Output	Power dissipation	P _C	150	mW
	Derating factor (above T _a = 100°C)		5.8	mW/°C
	Collector current	I _C	50	mA
	Collector-Emitter voltage	V _{CEO}	35	V
	Emitter-Collector voltage	V _{ECO}	6	V
Total Power Dissipation		P _{TOT}	200	mW
Isolation Voltage*1		V _{ISO}	5000	V rms
Operating Temperature		T _{OPR}	-55 to 110	°C
Storage Temperature		T _{STG}	-55 to 125	°C
Soldering Temperature*2		T _{SOL}	260	°C

Notes:

*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.

*2 For 10 seconds

Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	V _F	-	1.2	1.4	V	I _F = 20mA
Reverse Current	I _R	-	-	10	μA	V _R = 4V
Input capacitance	C _{in}	-	30	250	pF	V = 0, f = 1kHz

Note: Reverse Voltage(V_R) Condition is applied to I_R test only The device is not designed for reverse operation

Output

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Collector-Emitter dark current	I _{CEO}	-	-	100	nA	V _{CE} = 20V, I _F = 0mA
Collector-Emitter breakdown voltage	BV _{CEO}	35	-	-	V	I _C = 0.1mA
Emitter-Collector breakdown voltage	BV _{ECO}	6	-	-	V	I _E = 0.1mA

Transfer Characteristics

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Current Transfer ratio	EL817	50	-	600	%	I _F = 5mA, V _{CE} = 5V
	EL817A	80	-	160		
	EL817B	130	-	260		
	EL817C	200	-	400		
	EL817D	300	-	600		
	EL817X	100	-	200		
	EL817Y	150	-	300		
Collector-Emitter saturation voltage	V _{CE(sat)}	-	0.1	0.2	V	I _F = 20mA, I _C = 1mA
Isolation resistance	R _{IO}	5×10 ¹⁰	-	-	Ω	V _{IO} = 500Vdc, 40~60% R.H.
Floating capacitance	C _{IO}	-	0.6	1.0	pF	V _{IO} = 0, f = 1MHz
Cut-off frequency	f _c	-	80	-	kHz	V _{CE} = 5V, I _C = 2mA, R _L = 100Ω, -3dB
Rise time	t _r	-	-	18	μs	V _{CE} = 2V, I _C = 2mA, R _L = 100Ω
Fall time	t _f	-	-	18	μs	

* Typical values at T_a = 25°C

Typical Electro-Optical Characteristics Curves

Figure 1. Forward Current vs Forward Voltage

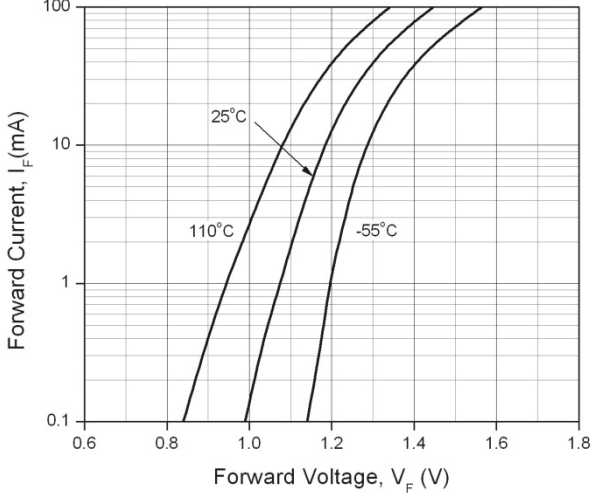


Figure 2. Normalized Current Transfer Ratio vs Forward Current

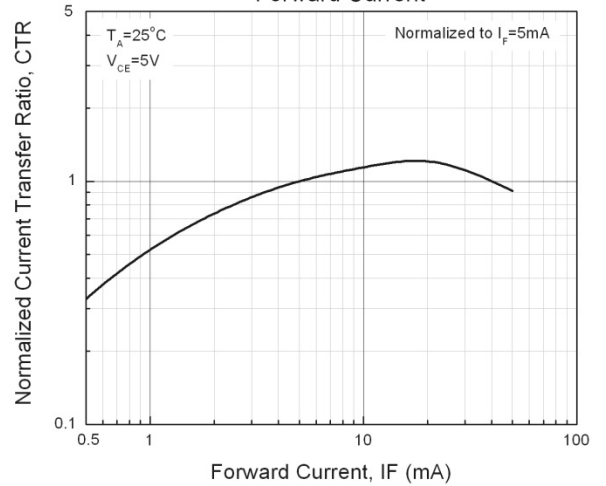


Figure 3. Current Transfer Ratio vs Ambient Temperature

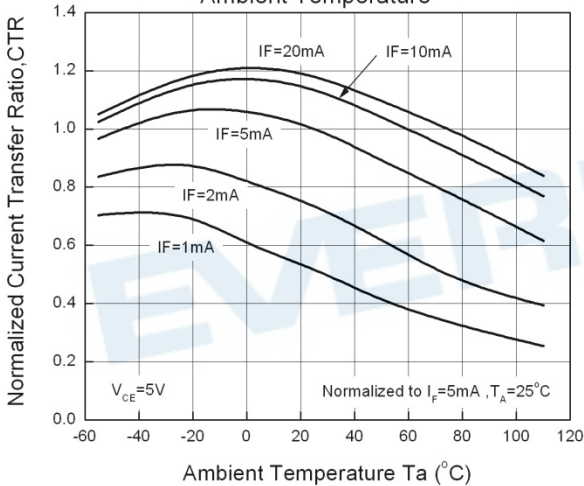


Figure 4. Dark Current vs Ambient Temperature

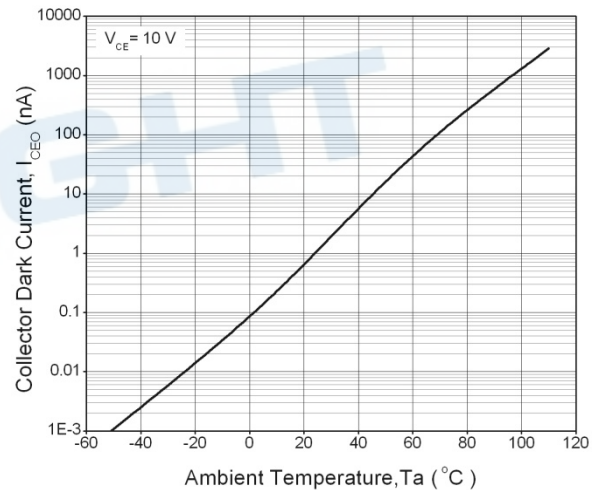


Figure 5. Collector-Emitter Saturation Voltage vs Collector Current

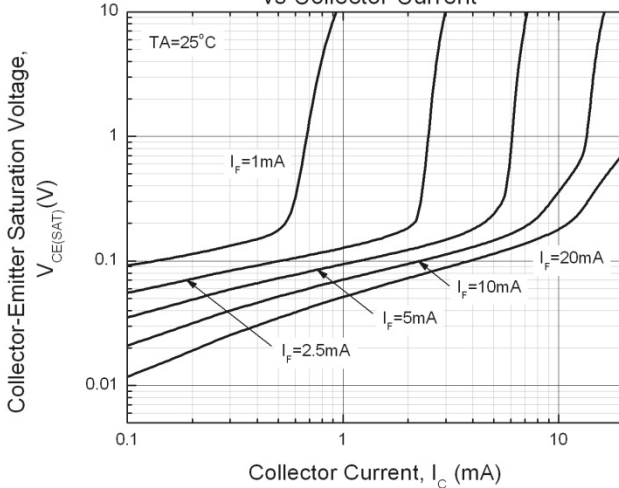
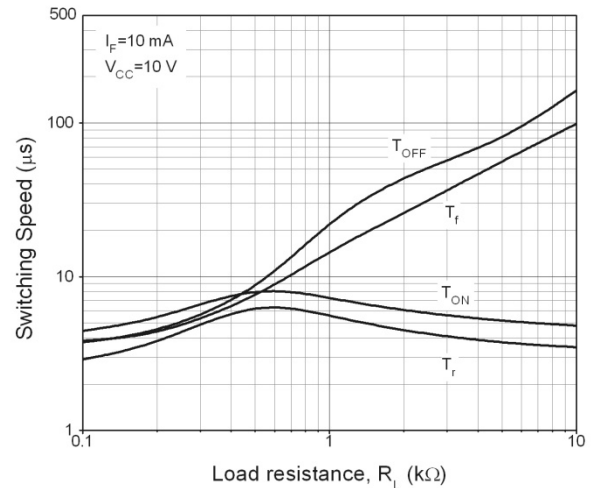
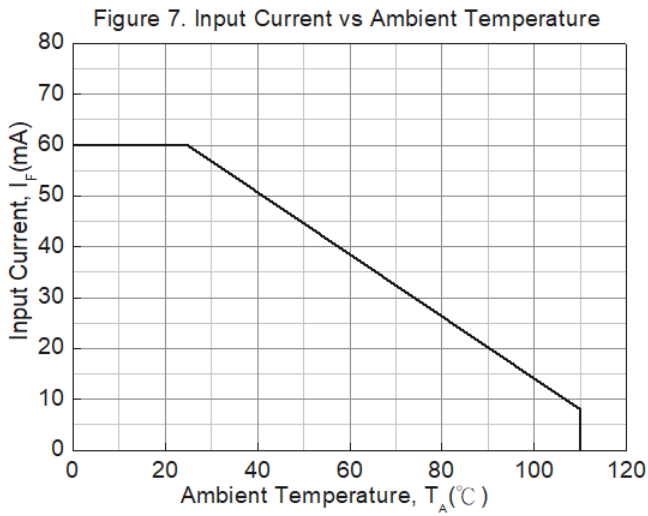


Figure 6. Switching Time vs Load Resistance





Note : The graphs shown in this datasheet are representing typical data only and do not show guaranteed values

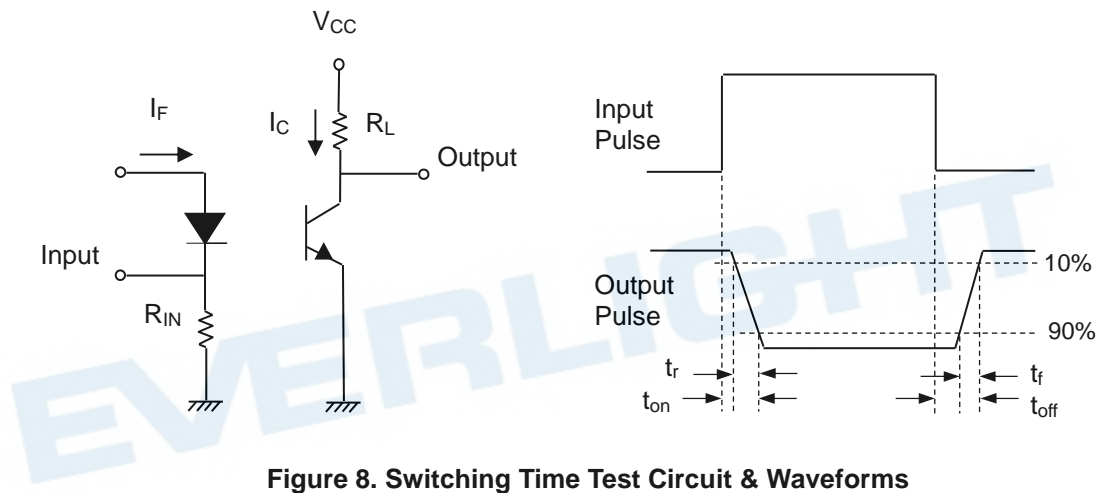


Figure 8. Switching Time Test Circuit & Waveforms

Order Information

Part Number

EL817X(Y)(Z)-FV

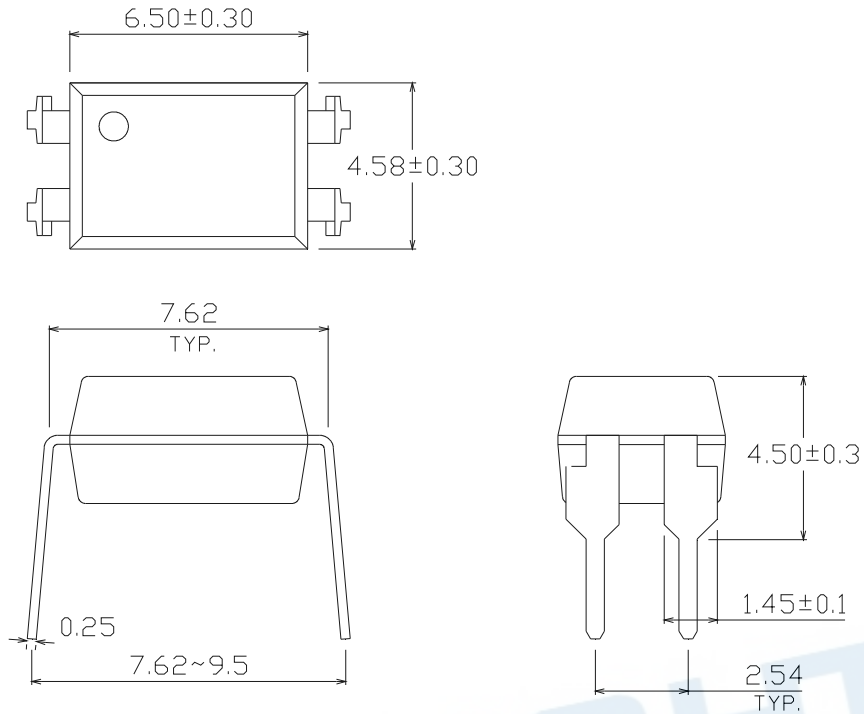
Note

- X = Lead form option (S1, S2, M or none)
- Y = CTR Rank (A, B, C, D, X, Y or none)
- Z = Tape and reel option (TU, TD or none)
- F = Lead frame option (F: Iron, None: copper)
- V = VDE safety (optional)

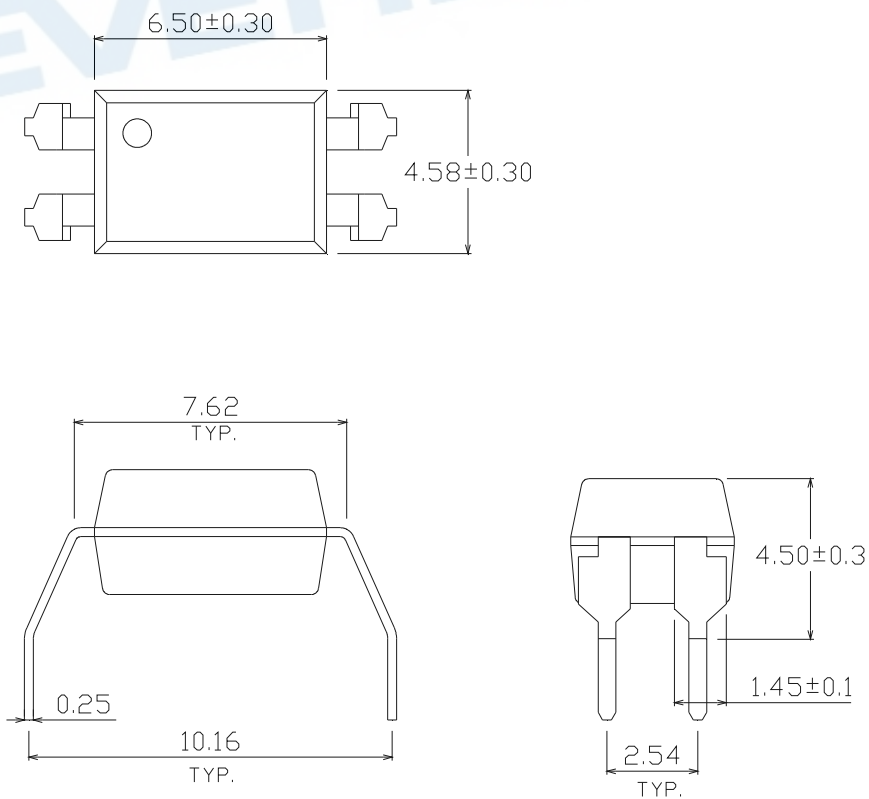
Option	Description	Packing quantity
None	Standard DIP-4	100 units per tube
M	Wide lead bend (0.4 inch spacing)	100 units per tube
S1 (TU)	Surface mount lead form (low profile) + TU tape & reel option	2000 units per reel
S1 (TD)	Surface mount lead form (low profile) + TD tape & reel option	2000 units per reel
S2 (TU)	Surface mount lead form (low profile) + TU tape & reel option	2000 units per reel
S2 (TD)	Surface mount lead form (low profile) + TD tape & reel option	2000 units per reel

Package Dimension (Dimensions in mm)

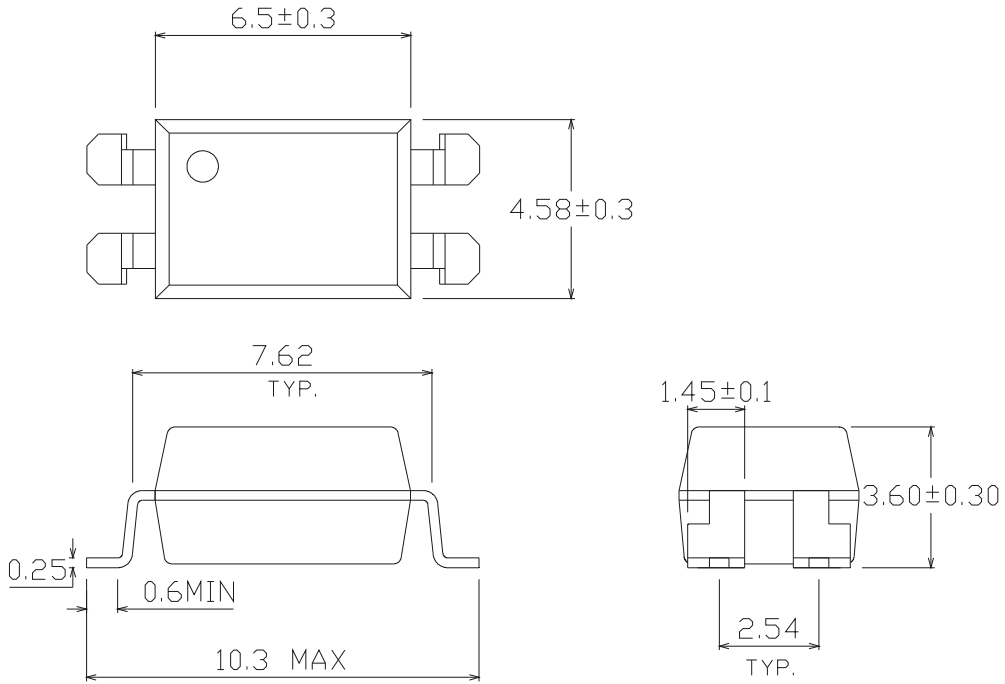
Standard DIP Type



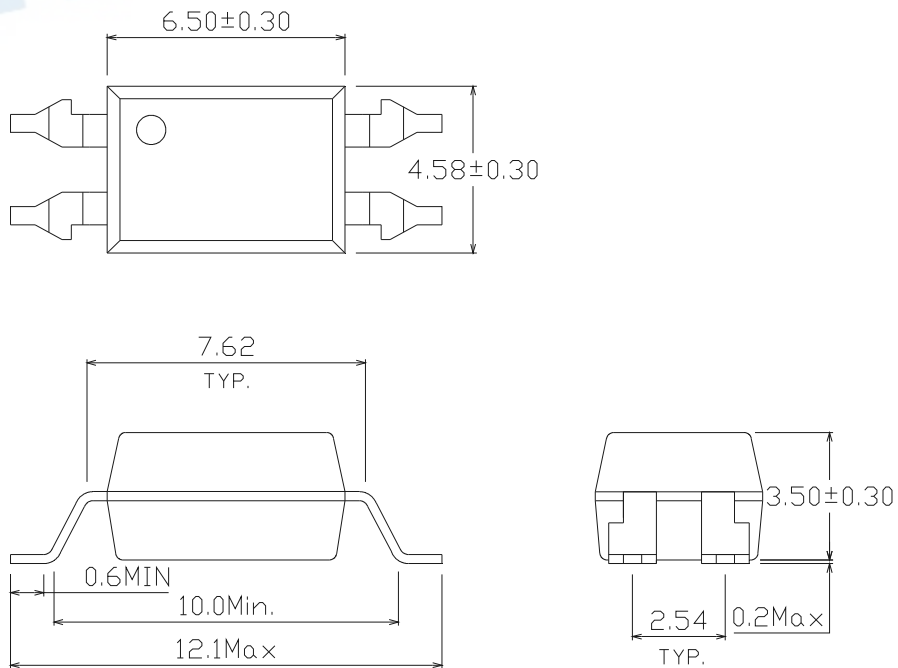
Option M Type



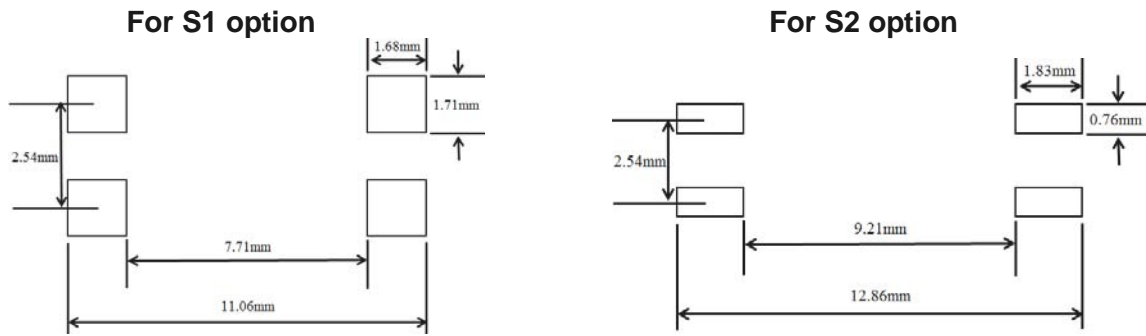
Option S1 Type



Option S2 Type



Recommended pad layout for surface mount leadform



Notes

Suggested pad dimension is just for reference only.
Please modify the pad dimension based on individual need.

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Device Marking








Notes




EL	denotes EVERLIGHT
817	denotes Device Number
R	denotes CTR Rank (A, B, C, D, X, Y or none)
Y	denotes 1 digit Year code
WW	denotes 2 digit Week code
V	denotes VDE (optional)

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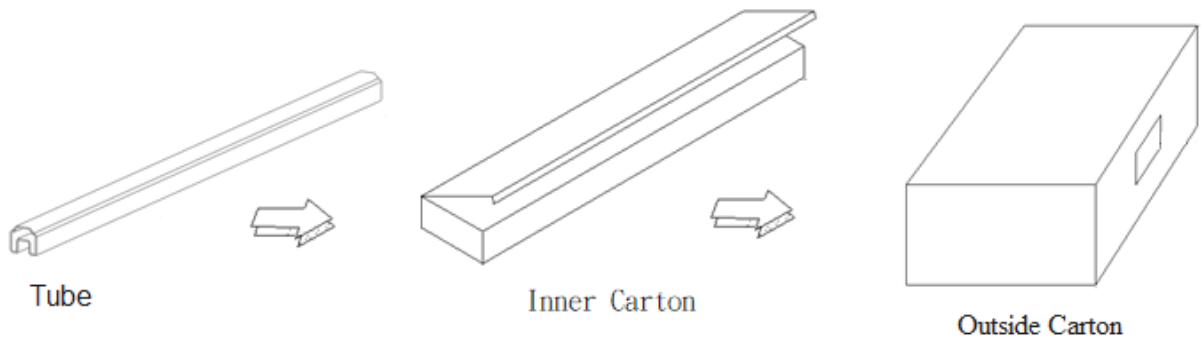
Label form


EVERLIGHT
11 → 月份
 → RoHS標示
 → 安規標示
 客戶料號 ← CPN: XXXXXXXXXXXX 測試區
 億光料號 ← P/N: XXXXXXXXXXXX
 億光品名 ← EL817M(C)-VG
 生產周別 ← D/C: YWWX CAT: X QTY: 000000
 → 包裝數量
 生產序號 ← LOT NO: Y151130XXXXXXXXXX
 標籤識別碼 ← REFERENCE: BTPyyMMddXXXXX
 → QR Code
 產地 ← MADE IN XXXXXX

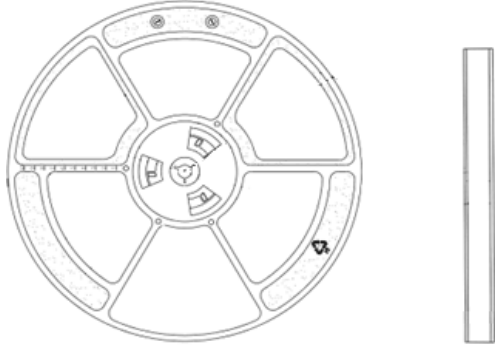
or

RoHS 標示

EVERLIGHT
5 → 月份
 → 安規標示
 客戶料號 ← CPN: XXXXXXXXXXXX 測試區
 客戶品名 ← XXXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXX
 億光料號 ← P/N: XXXXXXXXXXXX
 億光品名 ← XXXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXX
 生產序號 ← LOT NO: Y150516XXX-XXXXXXXXXX-XXXXXXXXXX
 包裝數量 ← QTY: 0123456789 HUE: XXXXXXXXXXXX
 CTR等級 ← CAT: XXXXXXXXXXXX REF: XXXXXXXXXXXX
 標籤識別碼 ← REFERENCE: BTPYMMDDXXXXX
 → QR Code
 MSL等級 ← MSL-XX MADE IN XXXXXX
 ↓
 產地

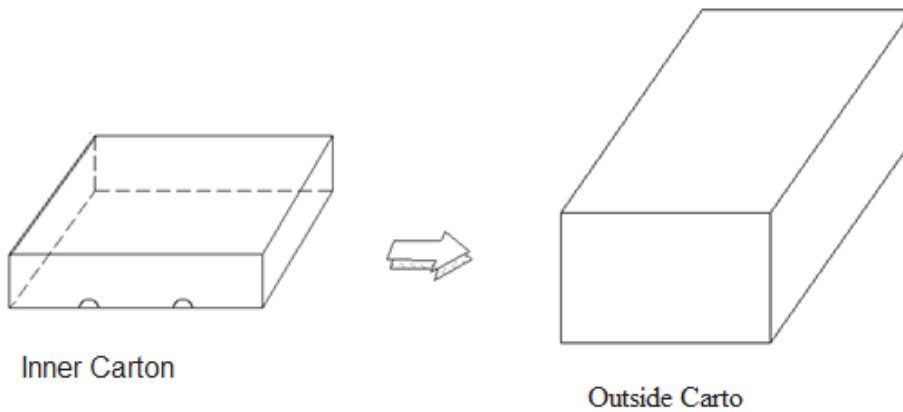
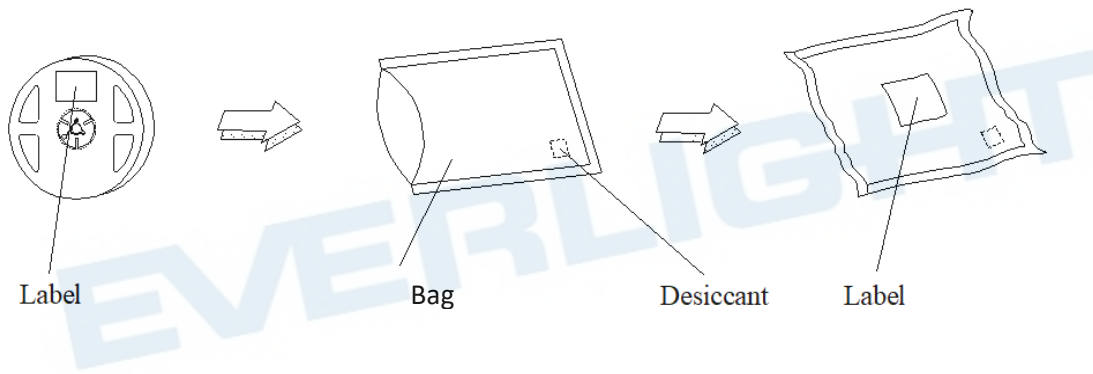
TUBE Dimension



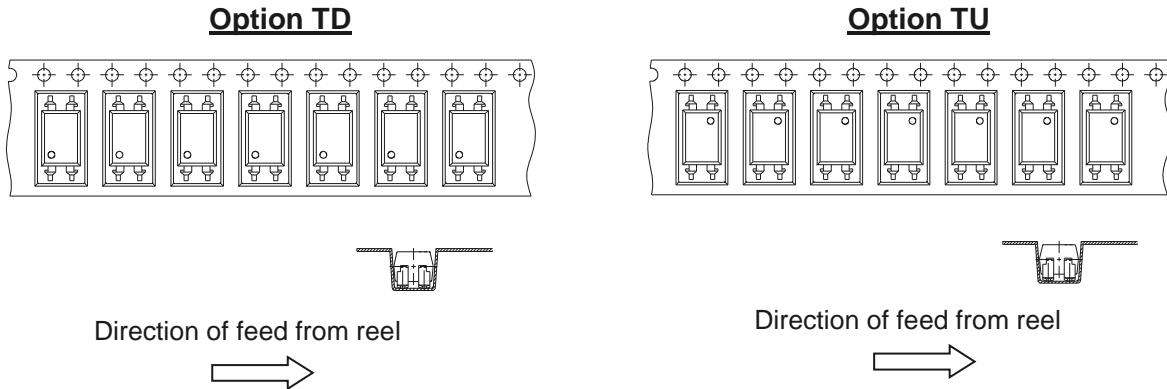
Reel Dimension



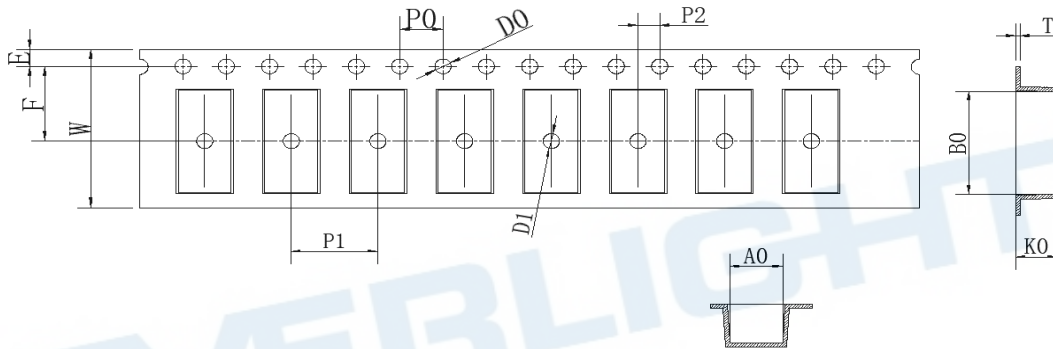
Moisture Resistant Packaging



Tape & Reel Packing Specifications



Tape dimensions

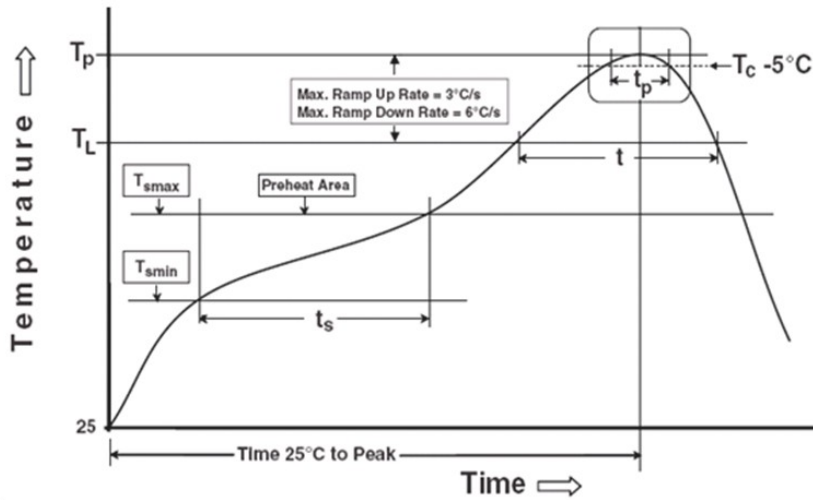


Dimension No.	Ao	Bo	Do	D1	E	F
Dimension (mm) S1	4.90±0.1	10.40±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.50±0.1
Dimension (mm) S2	4.88±0.1	12.55±0.1	1.5±0.1	1.50±0.1	1.75±0.1	11.5±0.1
Dimension No.	Po	P1	P2	t	W	Ko
Dimension (mm) S1	4.00±0.1	8.00±0.1	2.00±0.1	0.40±0.1	16.00±0.3	4.00±0.1
Dimension (mm) S2	4.00±0.1	8.00±0.1	2.00±0.1	0.40±0.1	24.00±0.3	4.00±0.1

Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T_{smin})	150 °C
Temperature max (T_{smax})	200°C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max

Other

Liquidus Temperature (T_L)	217 °C
Time above Liquidus Temperature (t_L)	60-100 sec
Peak Temperature (T_P)	260°C
Time within 5 °C of Actual Peak Temperature: $T_P - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

Precautions for General Storage

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5°C to 35°C and 20 % to 60 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

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DISCLAIMER

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2. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
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